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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









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SI4435DY

30V P-Channel PowerTrench® MOSFET

General Description

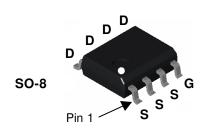
This P-Channel MOSFET is a rugged gate version of Fairchild Semiconductor's advanced PowerTrench process. It has been optimized for power management applications requiring a wide range of gave drive voltage ratings (4.5V-25V).

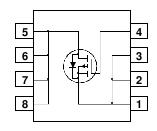
Applications

- Power management
- · Load switch
- · Battery protection

Features

- -8.8 A, -30 V $R_{DS(ON)} = 20 \text{ m}\Omega$ @ $V_{GS} = -10 \text{ V}$ $R_{DS(ON)} = 35 \text{ m}\Omega$ @ $V_{GS} = -4.5 \text{ V}$
- Low gate charge (17nC typical)
- Fast switching speed
- High performance trench technology for extremely low R_{DS(ON)}
- High power and current handling capability





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		-30	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Drain Current - Continuous	(Note 1a)	-8.8	Α
	Pulsed		-50	
P _D	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.2	
		(Note 1c)	1	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +175	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1c)	125	°C/W
R _{0JC}	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

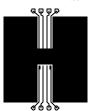
Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
SI4435DY	SI4435DY	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics				l	
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$, Referenced to 25°C		-21		mV/°C
loss	Zero Gate Voltage Drain Current	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μΑ
GSSF	Gate-Body Leakage, Forward	$V_{GS} = 20 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
GSSR	Gate-Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-1	-1.7	-3	V
ΔV _{GS(th)} ΔT _J	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu A$, Referenced to 25°C		5		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$V_{GS} = -10 \text{ V}, I_D = -8.8 \text{ A}$ $V_{GS} = -4.5 \text{ V}, I_D = -6.7 \text{ A}$ $V_{GS} = -10 \text{ V}, I_D = -8.8 \text{ A}, T_J = 125 ^{\circ}\text{C}$		15 22 19	20 35 32	mΩ
I _{D(on)}	On-State Drain Current	$V_{GS} = -10 \text{ V}, \qquad V_{DS} = -5 \text{ V}$	-40			Α
g FS	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -8.8 \text{ A}$		24		S
Dynamic	Characteristics	,			I	
C _{iss}	Input Capacitance	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V},$		1604		pF
Coss	Output Capacitance	f = 1.0 MHz		408		pF
C _{rss}	Reverse Transfer Capacitance			202		pF
Switchin	g Characteristics (Note 2)				I	
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -15 \text{ V}, \qquad I_D = -1 \text{ A},$		13	23	ns
t _r	Turn-On Rise Time	$V_{GS} = -10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		13.5	24	ns
t _{d(off)}	Turn-Off Delay Time			42	68	ns
t _f	Turn-Off Fall Time			25	40	ns
Qg	Total Gate Charge	$V_{DS} = -15 \text{ V}, I_{D} = -8.8 \text{ A},$		17	24	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = -5 \text{ V}$		5		nC
Q _{gd}	Gate-Drain Charge	1		6		nC
Drain-Se	ource Diode Characteristics	and Maximum Ratings				
ls	Maximum Continuous Drain-Source				-2.1	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -2.1 A (Note 2)		-0.73	-1.2	V

Notes:

R_{BUA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BUC} is guaranteed by design while R_{BCA} is determined by the user's board design.



a) 50°C/W when mounted on a 1irf pad of 2 oz copper



b) 105°C/W when mounted on a .04 in² pad of 2 oz copper



c) 125°C/W when mounted on a minimum pad.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width < $300\mu s,$ Duty Cycle < 2.0%

Typical Characteristics

I_D = -8.8A V_{GS} = -10V

R_{DS(ON)} NORMALIZED DRAIN-SOURCE ON-RESISTANCE

1.2

0.8

0.6

-50

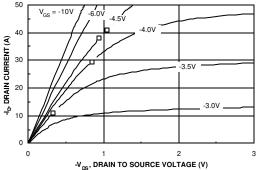


Figure 1. On-Region Characteristics.



150

Figure 3. On-Resistance Variation with Temperature.

50 75 100

T, JUNCTION TEMPERATURE (°C)

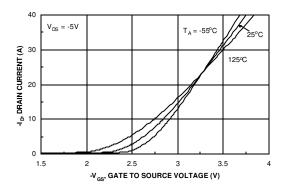


Figure 5. Transfer Characteristics.

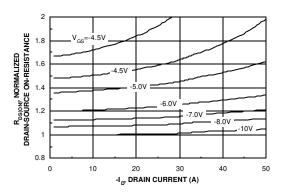


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

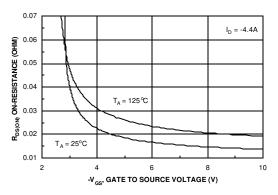


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

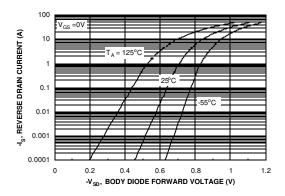
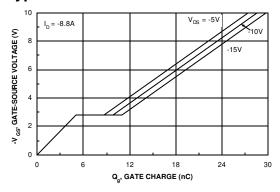


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



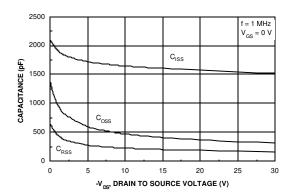
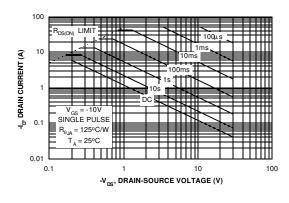


Figure 7. Gate Charge Characteristics.





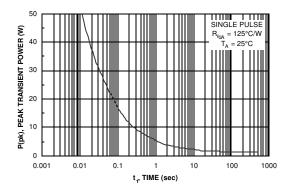


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

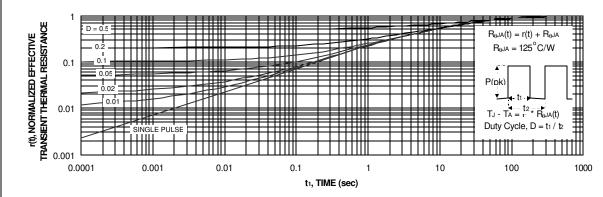


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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